



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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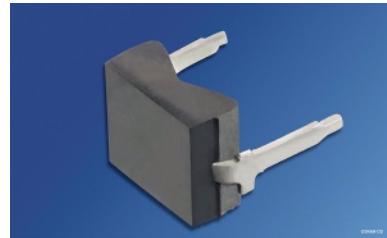
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# Silizium-Pin-Fotodiode mit Tageslichtsperrfilter; in SMT Silicon Pin Photodiode with Daylight Filter; in SMT

BP 104 F

BP 104 FS



BP 104 F



BP 104 FS

## Wesentliche Merkmale

- Speziell geeignet für Anwendungen bei 950 nm
- Kurze Schaltzeit (typ. 20 ns)
- DIL-Plastikbauform mit hoher Packungsdichte
- BP 104 FS: geeignet für Vapor-Phase Löten und IR-Reflow Löten

## Features

- Especially suitable for applications of 950 nm
- Short switching time (typ. 20 ns)
- DIL plastic package with high packing density
- BP 104 FS: suitable for vapor-phase and IR-reflow soldering

## Anwendungen

- IR-Fernsteuerung von Fernseh- und Rundfunkgeräten, Videorecordern, Lichtdimmern, Gerätefernsteuerungen
- Lichtschranken für Gleich- und Wechsellichtbetrieb

## Applications

- IR remote control of hi-fi and TV sets, video tape recorders, dimmers, remote controls of various equipment
- Photointerrupters

Typ Type	Bestellnummer Ordering Code	Gehäuse Package
BP 104 F	Q62702-P84	DIL-Gehäuse, schwarzes Epoxy-Gießharz, Kathodenkennzeichnung: Fähnchen am Anschluß DIL package, black epoxy resin Cathode marking: flag on lead
BP 104 FS	Q62702-P1646	DIL/SMT-Gehäuse, schwarzes Epoxy-Gießharz, Kathodenkennzeichnung: Langer, breiter Anschluß DIL/SMT package, black epoxy resin Cathode marking: long broad lead

**Grenzwerte****Maximum Ratings**

<b>Bezeichnung Parameter</b>	<b>Symbol Symbol</b>	<b>Wert Value</b>	<b>Einheit Unit</b>
Betriebs- und Lagertemperatur Operating and storage temperature range	$T_{\text{op}}; T_{\text{stg}}$	- 40 ... + 100	°C
Sperrspannung Reverse voltage	$V_R$	20	V
Verlustleistung, $T_A = 25$ °C	$P_{\text{tot}}$	150	mW

**Kennwerte ( $T_A = 25$  °C,  $\lambda = 950$  nm)****Characteristics**

<b>Bezeichnung Parameter</b>	<b>Symbol Symbol</b>	<b>Wert Value</b>	<b>Einheit Unit</b>
Fotostrom Photocurrent $V_R = 5$ V, $E_e = 1$ mW/cm <sup>2</sup>	$I_P$	34 ( $\geq 25$ )	µA
Wellenlänge der max. Fotoempfindlichkeit Wavelength of max. sensitivity	$\lambda_{S \text{ max}}$	950	nm
Spektraler Bereich der Fotoempfindlichkeit $S = 10\%$ von $S_{\text{max}}$ Spectral range of sensitivity $S = 10\%$ of $S_{\text{max}}$	$\lambda$	800 ... 1100	nm
Bestrahlungsempfindliche Fläche Radiant sensitive area	A	4.84	mm <sup>2</sup>
Abmessung der bestrahlungsempfindlichen Fläche Dimensions of radiant sensitive area	$L \times B$ $L \times W$	2.20 × 2.20	mm × mm
Abstand Chipoberfläche zu Gehäuseoberfläche Distance chip front to case surface	H	0.5 0.3 (BP 104 FS)	mm
Halbwinkel Half angle	Φ	± 60	Grad deg.
Dunkelstrom, $V_R = 10$ V Dark current	$I_R$	2 ( $\leq 30$ )	nA
Spektrale Fotoempfindlichkeit Spectral sensitivity	$S_\lambda$	0.70	A/W
Quantenausbeute Quantum yield	η	0.90	Electrons Photon

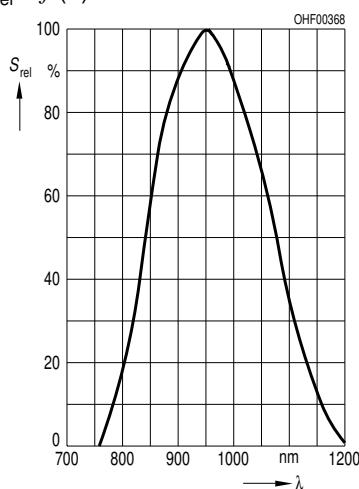
Kennwerte ( $T_A = 25^\circ\text{C}$ ,  $\lambda = 950 \text{ nm}$ )

Characteristics (cont'd)

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Leerlaufspannung, $E_e = 0.5 \text{ mW/cm}^2$ Open-circuit voltage	$V_O$	330 ( $\geq 250$ )	mV
Kurzschlußstrom, $E_e = 0.5 \text{ mW/cm}^2$ Short-circuit current	$I_{SC}$	17	$\mu\text{A}$
Anstiegs- und Abfallzeit des Fotostromes Rise and fall time of the photocurrent $R_L = 50 \Omega$ ; $V_R = 5 \text{ V}$ ; $\lambda = 850 \text{ nm}$ ; $I_p = 800 \mu\text{A}$	$t_r, t_f$	20	ns
Durchlaßspannung, $I_F = 100 \text{ mA}$ , $E = 0$ Forward voltage	$V_F$	1.3	V
Kapazität, $V_R = 0 \text{ V}$ , $f = 1 \text{ MHz}$ , $E = 0$ Capacitance	$C_0$	48	pF
Temperaturkoeffizient von $V_O$ Temperature coefficient of $V_O$	$TC_V$	- 2.6	mV/K
Temperaturkoeffizient von $I_{SC}$ Temperature coefficient of $I_{SC}$	$TC_I$	0.18	%/K
Rauschäquivalente Strahlungsleistung Noise equivalent power $V_R = 10 \text{ V}$	$NEP$	$3.6 \times 10^{-14}$	$\frac{\text{W}}{\sqrt{\text{Hz}}}$
Nachweisgrenze, $V_R = 10 \text{ V}$ Detection limit	$D^*$	$6.1 \times 10^{12}$	$\frac{\text{cm} \times \sqrt{\text{Hz}}}{\text{W}}$

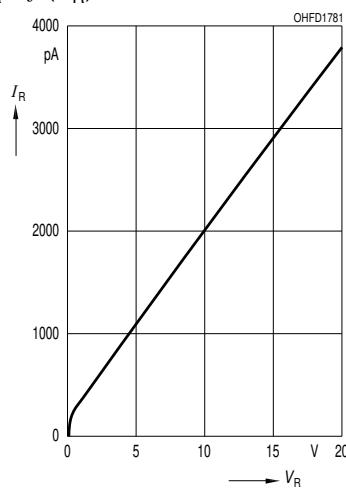
**Relative Spectral Sensitivity**

$$S_{\text{rel}} = f(\lambda)$$



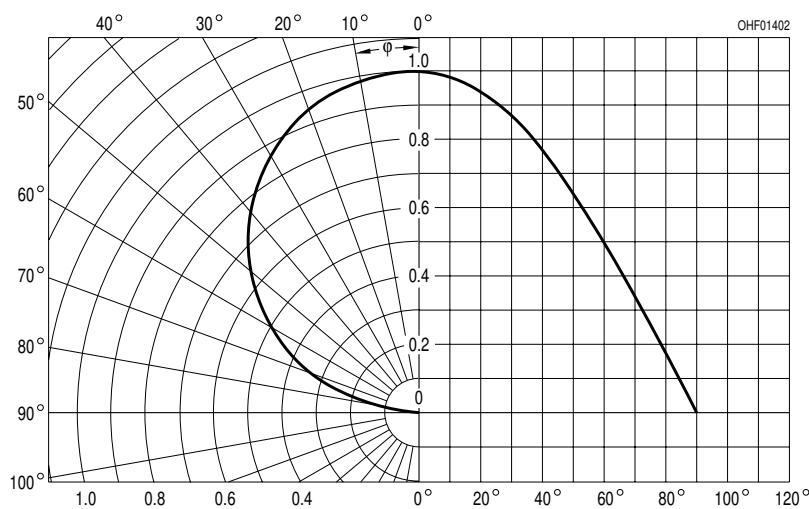
**Dark Current**

$$I_R = f(V_R), E = 0$$



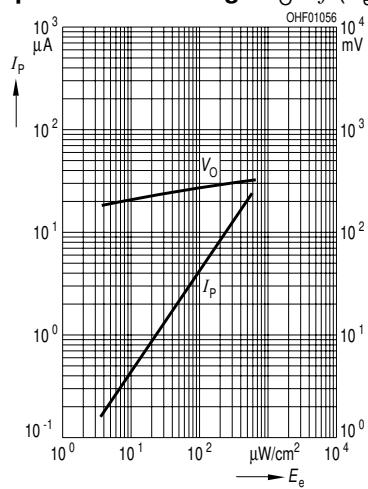
**Directional Characteristics**

$$S_{\text{rel}} = f(\phi)$$



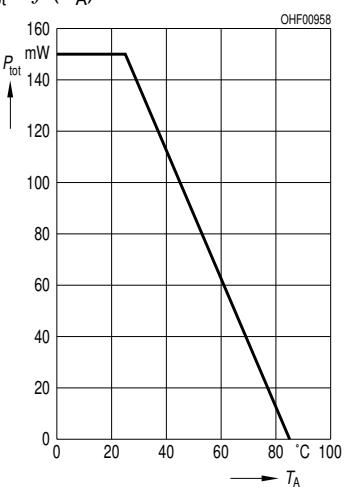
**Photocurrent  $I_P = f(E_e)$ ,  $V_R = 5 \text{ V}$**

**Open-Circuit Voltage  $V_O = f(E_e)$**



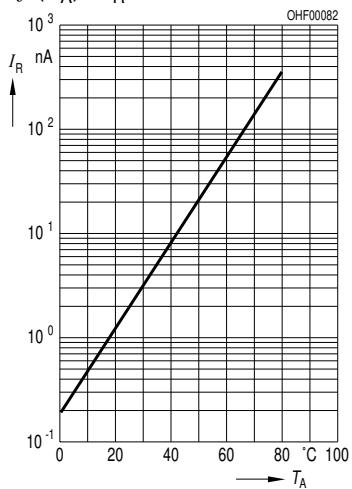
**Total Power Dissipation**

$$P_{\text{tot}} = f(T_A)$$



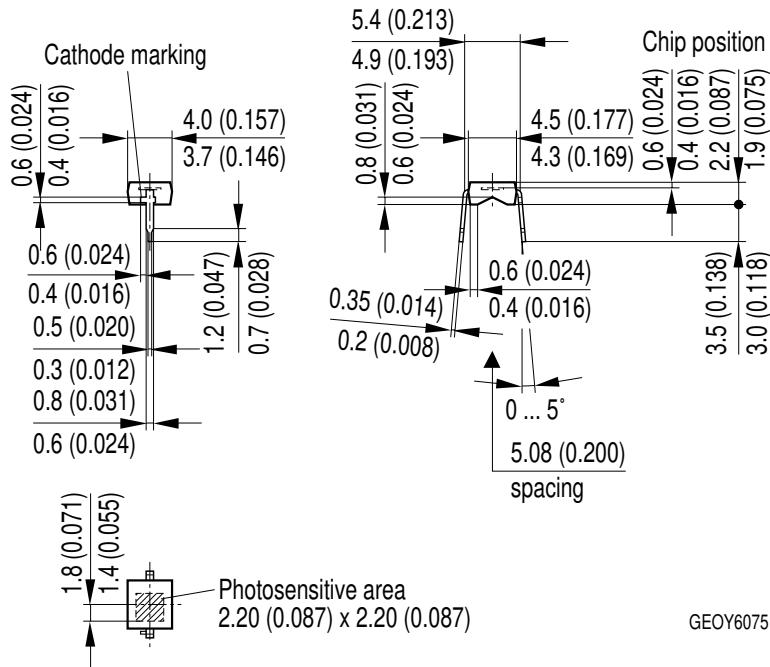
**Dark Current**

$$I_R = f(T_A), V_R = 10 \text{ V}, E = 0$$

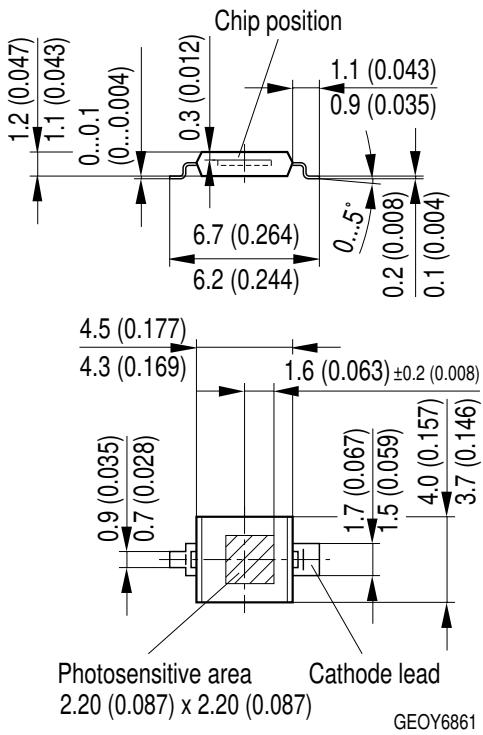


**Maßzeichnung  
Package Outlines**

BP 104 F



BP 104 FS



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

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**Attention please!**

The information describes the type of component and shall not be considered as assured characteristics.  
Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances. For information on the types in question please contact our Sales Organization.

**Packing**

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

**Components used in life-support devices or systems must be expressly authorized for such purpose!** Critical components<sup>1</sup>, may only be used in life-support devices or systems<sup>2</sup> with the express written approval of OSRAM OS.

<sup>1</sup> A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or effectiveness of that device or system.

<sup>2</sup> Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered.